



Material Composition Declaration

EPC2305

Company Name	Efficient Power Conversion (EPC)	Issue Date:	2/15/2024
Contact Name:	Yanping Ma	Contact Title:	VP Quality
Contact Phone:	(310) 615-0280	Contact Email:	yanping.ma@epc-co.com
Part Weight:	31.2 mg	Type of Product:	eGaN FET in FCQFN package

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	9.8279	31.5076	33.2129	315076
	Silicon oxide	7631-86-9	0.0775	0.2484		2484
	Silicon nitride	12033-89-5	0.0417	0.1337		1337
	Gallium nitride	25617-97-4	0.0836	0.2680		2680
	Aluminum	7429-90-5	0.1318	0.4225		4225
	Aluminum nitride	24304-00-5	0.0178	0.0569		569
	Titanium	7440-32-6	0.0046	0.0147		147
	Titanium nitride	25583-20-4	0.0262	0.0840		840
	Copper	7440-50-8	0.0022	0.0071		71
	Tungsten	7440-33-7	0.0088	0.0282		282
	Polyimide		0.1378	0.4418	4418	
Under Bump Metal	Titanium	7440-32-6	0.0010	0.0031	0.0341	31
	Copper	7440-50-8	0.0097	0.0310		310
Solder Bump	Copper	7440-50-8	0.8115	2.6016	3.5547	26016
	Nickel	7440-02-0	0.0576	0.1847		1847
	Tin	7440-31-5	0.2354	0.7546		7546
	Silver	7440-22-4	0.0043	0.0138		138
Package	Copper	7440-50-8	11.7262	37.5936	63.1982	375936
	Iron	7439-89-6	0.3007	0.9639		9639
	Mold Compound		7.0000	22.4416		224416
	Tin	7440-31-5	0.6859	2.1990		21990
Sum in total:			31.1921	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.